

Name of the part	Pb	Cd	Hg	Cr-VI	PBB	PBDE
Die	0	0	0	0	0	0
Lead Frame	0	0	0	0	0	0
Mould Compound	0	0	0	0	0	0
Post-plating	0	0	0	0	0	0
Solder Wire	0	0	0	0	0	0
Wire	0	0	0	0	0	0

0: Indicates all homogeneous materials` hazardous substances content are below the SJ/T11363-2006 limit.

X: Indicates that the hazardous substance content contained in any one of the homogenous materials of the part exceeded the MCV limits specified in the Standard SJ/T 11363-2006.

Remark: All WeEn Semiconductors products have an environmental friendly use period (EFUP) of 50 years.

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